

Final Product/Process Change Notification Document #: FPCN22653X

Issue Date: 15 May 2019

Title of Change:	Qualification of ON Semiconductor, Tarlac, Philippines as the extended assembly location for NCP81278TMNTXG and NCP81269MNTXG products.		
Proposed first ship date:	22 August 2019		
Contact information:	Contact your local ON Semiconductor Sales Office or < <u>clarence.wong@onsemi.com</u> >		
Samples:	Contact your local ON Semiconductor Sales Office or <pcn.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</pcn.samples@onsemi.com>		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Andy.Esteva@onsemi.com >.		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < PCN.Support@onsemi.com >		
Change Part Identification:	Parts can be identified through date code marking following ON Semiconductor standards. Contact your local ON Semiconductor Sales Office for the specific date code information.		
Change Category:	☐ Wafer Fab Change	Test Change Other	
Change Sub-Category(s): ✓ Manufacturing Site Addition ✓ Material Change ✓ Manufacturing Site Transfer ✓ Manufacturing Process Change		☐ Datasheet/Product Doc change ☐ Shipping/Packaging/Marking ☐ Other:	
Sites Affected:	ON Semiconductor Sites: ON Tarlac City, Philippines	External Foundry/Subcon Sites: None	

Description and Purpose:

ON Semiconductor is expanding the subject products assembly capacity via addition of internal assembly site in the supply chain.

There is no change to the datasheet specifications, or any other aspect of the product.

Before Change Description		After Change Description	
Addition of Product Assembly Site	Products only from external assembly facility (UTL, Thailand)	Products from both ON Internal Assy Site (ON Semiconductor, Tarlac, Philippines) and external assembly facility (UTL, Thailand).	
Lead Finish	Matte Tin = Sn = e3	UTL : Matte Tin = Sn = e3 OSPI Tarlac: PPF = NiPdAu = e4	
Marking (Assembly Site code)	UTL = G	UTL = G OSPI TARLAC = MP	

There is no product marking change as a result of this change.

TEM001793 Rev. C Page 1 of 2



Final Product/Process Change Notification Document #: FPCN22653X

Issue Date: 15 May 2019

Reliability Data Summary:

QV DEVICE NAME: NCP81278TMNTX6; NCP5269MNTWG

Test	Specification	Condition	Interval	Results
HTOL JESD22-A108		Ta=125°C, 100 % max rated Vcc	1008 hrs	0/80
HTSL JESD22-A103		Ta= 150C	1008 hrs	0/90
TC JESD22-A104		Ta= -65°C to +150°C	500 cyc	0/95
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/80
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/80
PC J-STD-020 JESD-A113		MSL 3IR @ 250 °C		0/175
RSH JESD22- B106		265°C Immersion		0/15
SD	JSTD002	Ta = 245°C		0/ 15

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the PCN Customized Portal.

Part Number	Qualification Vehicle	
NCP81278TMNTXG	NCP81278TMNTX6 NCP5269MNTWG	
NCP81269MNTXG	NCP81278TMNTX6 NCP5269MNTWG	

TEM001793 Rev. C Page 2 of 2